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FORM PTO-1595 U.S. DEPARTMENT OF COM	06-13-2001		ANOSIC	
1-31-92		ER SHEETJC03 Rec't	Patent and Trademark Office	
7217/64321	101747085	LY	GT/PTO 2.4 APR 2001	
To the Honorable Commissioner	101747000	d original documents or copy		
Name of conveying party(ies):	121/01	Name and address of receiving	g party(ies):	
Akira Shinada 0 4	129101	N 6. 6		
Aditional name(s) of conveying part	v(ies) attached Yes X No	Name: Sony Corporation Internal Address:		
	,(100) 1111101109. 22 110			
3. Nature of Conveyance:				
[편]	П.,	Street Address: 7-35 Kitashinaga Shinagawa-ku, Toky		
Assignment	L Merger			
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Other		Additional name(s) & address(es)	attached? Yes No	
Execution Date: April 1, 2001 4. Application number(s) or patent nu	imber(s):			
Tippheation nameer(s) or patent ne				
If this document is being filed together	with a new application, the execution date	of the application is April 1, 2001		
A. Patent Application No.(s)		B. Patent No.(s)		
109/23/	ア/フ			
07/800	Additional numbers attached?			
Name and address of party to who concerning document should be ma	-	6. Total number of applications :	and patents involved: L1	
Name: Jay H. Maioli Internal Address: Cooper & Dunh	om LLD	7. Total fee (37 CFR 3.41):	\$ 40.00	
Internat Address: Cooper & Dutin	am LLP		40.00	
		≭ Enclosed		
		Authorized to be ch	arged to deposit account	
Street Address: 1185 Avenue of	the Americas	8. Deposit account number:	arged to deposit account	
		03-3125		
		(Attach duplicate copy of this page	ge if paying by deposit account)	
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9. Statement and signature.				
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy				
of the original document.				
Jay H. Maioli, Reg. No.27,213	-ay Maroli	April 24, 2001		
Name of Person Signing	Signature	Date		
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PATENT REEL: 011878 FRAME: 0470

Docket No.	
S00P0987U	S 00
SKOOPCT79	ZII

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

<u>DATA RECORDING MEDIUM, DATA REPRODUCING METHOD AND</u> REPRODUCING DEVICE, AND DATA PROCESSING SYSTEM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35, Kitashinagawa 6-chome, Shinagawa-ku, Tokyo 141-0001 Japan (hereinafter reference as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereof;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

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Docket No	
<u>S</u>	00P0987US00
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And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereof;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

International Application Number PCT/JP00/05769

International Filing Date August U.S. Serial Number	
U.S. Filing Date	
This assignment executed on the	
Yoichiro SAKO	March 12, 2001
Name of first or sole inventor	Date
Tokyo, Japan	
Residence of first or sole inventor	
Signature of first or sole inventor	Execution date of U.S. Patent Application
Masanobu YAMAMOTO	Mar. 21, 200
Name of second inventor	Date
Kanagawa, Japan Residence of second inventor	
Masanolus Gamanoto	
Signature of second inventor	Execution date of U.S. Patent Application
	M. (3) o n (
Takao IHASHI	Mar 13. 200 (
Name of third inventor	Date
Chiba, Japan Residence of third inventor	
Residence of third inventor	
Tiguashir Signature of third inventor	
Signature of third inventor	Execution date of U.S. Patent Application

Docket No. S00P0987US00 SK00PCT79US

Tatsuya INOKUCHI Name of fourth inventor Kanagawa, Japan Residence of fourth inventor Signature of fourth inventor Execution date of U.S. Patent Application March 14. 200/ Kaoru KIJIMA Name of fifth inventor Tokyo, Japan Residence of fifth inventor Execution date of U.S. Patent Application Signature of fifth inventor

RECORDED: 04/24/2001

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